



DATE: 26 September, 2023

PCN #: 2641

PCN Title: Lead Frame Type, Die Bond Process, Wire Bond Type and Mold Compound changes to enhance select TO-252 packaged products.

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE**PCN-2641 REV 1**

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
26 September, 2023	26 December, 2023	Discrete	Assembly Bill of Materials	2641
TITLE				
Lead Frame Type, Die Bond Process, Wire Bond Type and Mold Compound changes to enhance select TO-252 packaged products				
DESCRIPTION OF CHANGE				
<p>This PCN is being issued to notify customers that in order to improve TO-252 package body strength and manufacturability, Diodes has qualified enhanced lead frame type with bare copper, die bond process with soft solder, PdCu wire bond and new mold compound type for the attached TO-252 packaged products.</p> <p>Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure there is no change to device functionality or electrical specifications in the datasheet.</p> <p>There will be no change to Form, Fit or Function of products affected.</p>				
IMPACT				
No change in datasheet electrical parameters and product performance.				
PRODUCTS AFFECTED				
Please refer to the attached part list below.				
WEB LINKS				
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/			
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/			
Data Sheet:	https://www.diodes.com/catalog/			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

Affected Part List					
2DB1182Q-13*	MJD31C-13*	MJD350-13	ZXT790AKTC*	ZXT951KTC*	ZXTN04120HKTC**
2DB1184Q-13*	MJD32C-13*	ZXT1053AKTC*	ZXT849KTC*	ZXT953KTC*	ZXTN4004KTC*
DXT696BK-13	MJD340-13	ZXT690BKTC*			

Note: "*" Change bond wire from Au to PdCu

Note: "**" Change bond wire from Cu to PdCu